



2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: HUEMOELLER, ET AL. DOCKET NO.: W2K1057
SERIAL NO: 09/931,144 EXAMINER: NORRIS, JEREMY C.
FILED: 08/16/01 ART UNIT: 2827

TITLE: SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT
SUBSTRATE AND METHOD THEREFOR

Assistant Commissioner
of Patents
Washington, D.C. 20231

Weiss & Moy, P.C.
4204 North Brown Avenue
Scottsdale, Arizona 85251-3989

March 13, 2003

I hereby certify that on the 13th day of March, 2003, this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Andrew M. Harris / sgh
Andrew M. Harris

Dear Sir:

AMENDMENT

This is in response to the Office Action dated December 19, 2002 in regards to the above-identified patent application.

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